



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu – SIG	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2104 mm	FR4 natural	4.5	0.02
In1.Cu – PWR	copper		0.0152 mm		1	0
Dielectric 2	core	FR4	1.065 mm	FR4 natural	4.5	0.02
In2.Cu – GND	copper		0.0152 mm		1	0
Dielectric 3	prepreg	FR4	0.2104 mm	FR4 natural	4.5	0.02
B.Cu – SIG	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6062 mm
Board overall dimensions:	116.0000 mm x 73.0000 mm	Min hole diameter:	0.3000 mm
Min track/spacing:	0.1000 mm / 0.0000 mm	Impedance Control:	Yes
Copper Finish:	HAL lead-free	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		